

# Specifications

Drawing No.	USY1M-H1-15384-00	1 / 8
Issued Date.	Jul,28,2015	

## Messrs: Digi-key

**Note: Part Number will be revised in case of specification change.**

Product Type	Quartz Crystal
Series	CX2016DB
Frequency	32000kHz
Customer Part Number	-
Customer Specification Number	-
KYOCERA Part Number	CX2016DB32000D0WZRC1
Remarks Pb-Free, RoHS Compliant, MSL 1	

### Customer Approval

Approval Signature	Approved Date	
	Department	
	Person in charge	

#### **Seller**

**KYOCERA Crystal Device Corporation**  
 (Sales Division)  
 6 Takeda Tobadono-cho, Fushimi-ku, Kyoto  
 612-8501 Japan  
 TEL. No. 075-604-3500  
 FAX. No. 075-604-3501

#### **Manufacturer**

**KYOCERA Crystal Device Corporation**  
 Crystal Units Division  
 5850, Higashine-Koh, Higashine-Shi, Yamagata  
 999-3701 Japan  
 TEL. No. 0237-43-5611  
 FAX. No. 0237-43-5615

Design Department	Quality Assurance	Approved by	Checked by	Issued by
KYOCERA Crystal Device Corporation Crystal Unit Application Engineering Section Crystal Units Division	S.Itoh	T.Soda	A.Muraoka	Y.Nozaki

### Revision History

Rev.No.	Description of revise	Date	Approved by	Checked by	Issued by
00	First Edition	Jul,28,2015	T.Soda	A.Muraoka	Y.Nozaki

### 1. APPLICATION

The purpose of this document is applied to CX2016DB quartz crystal.

### 2. KYOCERA PART NUMBER

CX2016DB32000D0WZRC1

### 3. RATINGS

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature range	Topr	-25~+75	deg. C	
Storage Temperature range	Tstg	-40~+85	deg. C	

### 4. CHARACTERISTICS

#### 4-1 ELECTRICAL CHARACTERISTICS

Items	Electrical Specification					Test Condition	Remarks
	SYMB.	Min	Typ.	Max	Unit		
Mode of Vibration		Fundamental					
Nominal Frequency	F0		32		MHz		
Nominal Temperature	T <sub>NOM</sub>		25		deg. C		
Load Capacitance	CL		8.0		pF		
Frequency tolerance	df/F					25deg.C	
Frequency Temperature Characteristics	df/t	-40.0		+40.0	PPM	-25~+75deg.C	
Frequency Aging Rate						25deg.C	1 <sup>st</sup> year
Equivalent Series Resistance	ESR			50	Ohms	CL=SERIES	
Shunt Capacitance	C0			3.0	pF		
Drive Level	Pd	0.01		100	μW		
Insulation Resistance	IR	500			M ohms	100V(DC)	

#### Measurement Condition

Frequency measurement

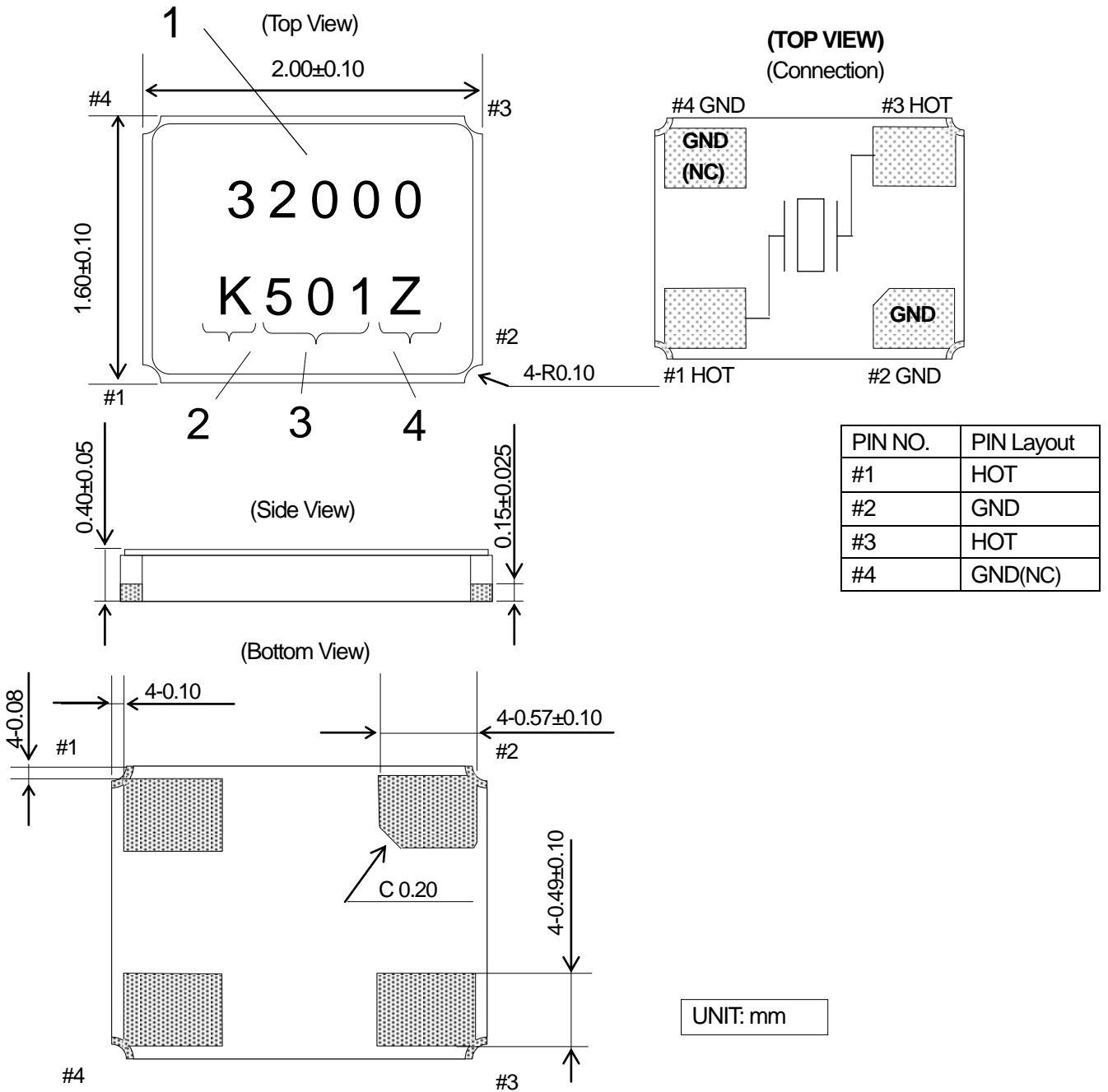
Measuring instrument : IEC PI-Network Test Fixture

Equivalent series resistance (ESR) measurement

Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : Series

**5. APPEARANCES, PHYSICAL DIMENSION**  
**OUTLINE DIMENSION (not to scale)**

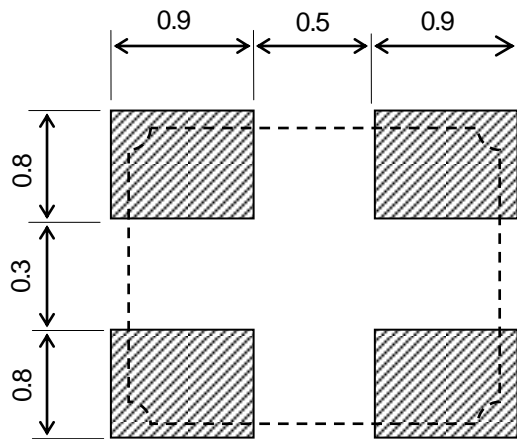


**MARKING**

- |   |                        |   |
|---|------------------------|---|
| 1 | Nominal Frequency      | First 5digit of the frequency is indicated.                   |
| 2 | Identification         | [K] is to indicate 1Pin direction.                            |
| 3 | Date Code              | Last 1 Digit of YEAR and WEEK (Ex) 2015,Jan,01 → 501          |
| 4 | Manufacturing Location | Y→Japan (Yamagata)<br>Z→Japan (Shiga Yohkaichi)<br>T→Thailand |

\*The font of marking is for reference only.

**6. RECOMMENDED LAND PATTERN (not to scale)**



UNIT : mm



7.6 Resistance to Moisture

Test condition

The quartz crystal unit shall be stored at a temperature of  $+60\pm 2^{\circ}\text{C}$  with relative humidity of 90% to 95% for 240 h. Then it shall be subjected to room temperature for 1h before measurement.

7.7 Soldering condition

1.) Type of solder

Material → lead free solder paste

Melting point →  $+220\pm 5^{\circ}\text{C}$

2.) Reflow temp.profile

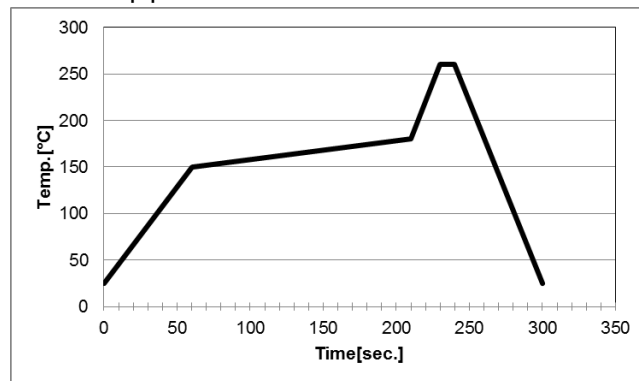
	Temp [ $^{\circ}\text{C}$ ]	Time[sec]
Preheating	+150 to +180	150 (typ.)
Peak	$+260\pm 5$	10 (max.)
Total	-	300 (max.)

Frequency shift :  $\pm 2\text{ppm}$

3.) Hand Soldering  $+350^{\circ}\text{C}$  3 sec max

4.) Reflow Times 2 times in below Reflow temp. profile

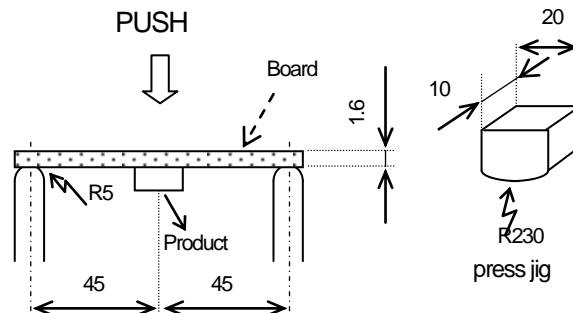
Reflow temp.profile



7.8 Bending Strength

Solder this product in center of the circuit board (40mm X 100mm), and add deflection of 3mm.

Test board :  $t=1.6\text{mm}$



UNIT : mm

## 8. Cautions for use

### (1) Soldering upon mounting

There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.

### (2) When using mounting machine

Please minimize the shock when using mounting machine to avoid any excess stress to the product.

### (3) Conformity of a circuit

We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 3 times the ESR (Equivalent Series Resistance) of crystal unit.

## 9. Storage conditions

Please store product in below conditions, and use within 6 months.

Temperature +18 to +30°C, and Humidity of 20 to 70 % in the packaging condition.

## 10. Manufacturing location

Kyocera Crystal Device Corporation Yamagata Plant

Kyocera Crystal Device Corporation Shiga Yohkaichi Plant

Kyocera Crystal Device (Thailand) Co., Ltd

## 11. Quality Assurance

To be guaranteed by Kyocera Crystal Device Quality Assurance Division

## 12. Quality guarantee

In case when Kyocera Crystal Device Corporation rooted failure occurred within 1year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1year of its delivery is waived.

## 13. Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.